samtec

E.L.P.™
EXTENDED LIFE PRODUCT
10 year Mixed Flowing Gas with 50µ" Gold
Call Samtec for maximum mated cycles

BSH–060–01–F–D–RA–WT

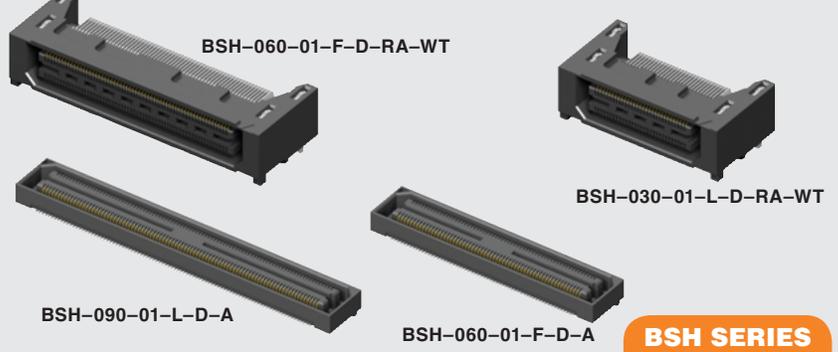BSH–030–01–L–D–RA–WT

BSH–090–01–L–D–A

BSH–060–01–F–D–A

BSH SERIES

(0,50 mm) .0197"

BASIC BLADE & BEAM SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?BSH

Insulator Material: Black LCP
Contact Material: Phosphor Bronze
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2 A per pin (1 pin powered per row)
Flammability Rating: UL 94 VO
Operating Temp Range: -55°C to +125°C
Voltage Rating: 275 VAC
Max Cycles: 100
RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (030-090) (0,15 mm) .006" max (120-150)
Board Stacking: For applications requiring more than two connectors per board or 90 positions or higher, contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
–01	(5,00) .197

*Processing conditions will affect mated height.

ALSO AVAILABLE
(MOQ Required)

- 30µ" (0,76 µm) Gold
- Edge Mount Capability
- 8 mm, 11 mm, 16 mm, 19 mm and 22 mm Stack Height (Caution: Some automatic placement/ inspection machines may have component height restrictions. Please consult machinery specifications.) (11 mm, 16 mm, 19 mm and 22 mm not available with 50 positions)

Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

BSH — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **A** — **OTHER OPTION**

Mates with:
BTH

–030, –050, –060, –090, –120, –150

No. of Positions x (0,50) .01969 + (6,27) .247

(6,22) .245

02

01

(0,50) .01969

(3,81) .150

(7,24) .285

(3,05) .120

(0,15) .006

(3,25) .128

(0,89) .035 DIA

(0,76) .030

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

–C*
= Electro-Polished Selective 50µ" (1,27 µm) min Au over 150µ" (3,81 µm) Ni on Signal Pins in contact area, Matte Tin over 50µ" (1,27 µm) min Ni on all solder tails

*Note: –C Plating passes 10 year MFG testing

–TR
= Tape & Reel (120 positions maximum)

AGILENT LOGIC ANALYZER TEST POINT CONNECTOR
Specify: ASP-65067-01

BSH — **NO. OF POSITIONS PER ROW** — **01** — **PLATING OPTION** — **D** — **RA** — **WT** — **OTHER OPTION**

Mates with:
BTH

–030, –060, –090

–F
= Gold Flash on contact, Matte Tin on tail

–L
= 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

–GP
= Guide Post

No. of Positions x (0,50) .01969 + (10,88) .428

(13,59) .535

01

(7,24) .285

02

(1,32) .052 x (1,10) .043

(0,15) .006

(0,50) .01969

(1,32) .052 DIA

(8,82) .347

(0,64) .025 SQ

Due to technical progress, all designs, specifications and components are subject to change without notice.